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### Fluid immersion cooling system with multiple layers of coolant fluids and method of using same

#### Abstract

A fluid immersion cooling system includes a fluid tank that contains a layer of a dual-phase coolant fluid and one or more layers of single-phase coolant fluids. The dual-phase and single-phase coolant fluids are immiscible, with the dual-phase coolant fluid having a lower boiling point and higher density than a single-phase coolant fluid. A substrate of an electronic system is submerged in the tank such that high heat-generating components are immersed at least in the layer of the dual-phase coolant fluid. Heat from the components is dissipated to the dual-phase coolant fluid to generate vapor bubbles of the dual-phase coolant fluid. The vapor bubbles rise to a layer of a single-phase coolant fluid that is above the layer of the dual-phase coolant fluid. The vapor bubbles condense to droplets of the dual-phase coolant fluid. The droplets fall down into the layer of the dual-phase coolant fluid.

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## References Cited

### U.S. PATENT DOCUMENTS

Patent No.	Issued Date	Patentee Name	U.S. Cl.	CPC
5472043	12/1994	Larson et al.	N/A	N/A
10123454	12/2017	Saito	N/A	H05K 7/20236
10985089	12/2020	Hart et al.	N/A	N/A
11435410	12/2021	Fitch et al.	N/A	N/A
2013/0019627	12/2012	Yoshikawa et al.	N/A	N/A
2013/0105120	12/2012	Campbell et al.	N/A	N/A
2014/0321053	12/2013	Donnelly	361/691	H01L 23/467
2015/0062806	12/2014	Shelnutt	361/679.53	H05K 7/20318
2017/0064862	12/2016	Miyoshi	N/A	N/A
2017/0325355	12/2016	Lau	N/A	N/A
2021/0102294	12/2020	Miljkovie et al.	N/A	N/A
2021/0153392	12/2020	Gao	N/A	N/A
2021/0185850	12/2020	Kulkarni et al.	N/A	N/A
2021/0221776	12/2020	Smith	N/A	F01K 25/10
2022/0264768	12/2021	Hornig	N/A	H05K 7/20327

### FOREIGN PATENT DOCUMENTS

Patent No.	Application Date	Country	CPC
101410685	12/2008	CN	N/A
110537257	12/2022	CN	N/A
249885	12/1994	TW	N/A

### OTHER PUBLICATIONS

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## **Background/Summary**

CROSS-REFERENCE TO RELATED APPLICATION (1) The present application is a continuation of U.S. application Ser. No. 17/383,607, filed on Jul. 23, 2021, now U.S. Pat. No. 12,029,012, which is incorporated herein by reference in its entirety.

### **BACKGROUND OF THE INVENTION**

#### **1. Field of the Invention**

(1) The present invention relates to fluid immersion cooling of electronic systems.

#### **2. Description of the Background Art**

(2) Electronic systems, such as information technology equipment (e.g., computers, routers, packet switches, cellular circuits), generate heat during operation. Cooling systems have been developed to prevent electronic systems from overheating. A simple cooling system involves the use of cooling fans to blow air towards heat-generating components of an electronic system. A more sophisticated approach is to submerge an electronic system in a coolant fluid (e.g., fluorochemical fluid), such as in a dual-phase fluid immersion cooling system. In a conventional dual-phase fluid immersion cooling system, heat generated by the electronic system turns a dual-phase coolant fluid into vapors, which rise to be collected by a condenser unit. The condenser unit is a piece of equipment that turns the vapors to liquid, which falls back down into the dual-phase coolant fluid, thereby completing the cooling cycle.

(3) Conventional dual-phase fluid immersion cooling systems demonstrate excellent power efficiency but have several disadvantages. First, there is risk that the vapors will leak into the environment. Leakage is especially concerning because vaporized dual-phase coolant fluid is considered to have a Global Warming Potential (GWP). Second, bellows, which are needed for vapor balance in a conventional dual-phase fluid immersion cooling system, take too much space. Third, because of the high potential for leakage, conventional dual-phase fluid immersion cooling systems are relatively expensive to manufacture and operate.

### **SUMMARY**

(4) In one embodiment, a fluid immersion cooling system includes a fluid tank that contains a layer of a dual-phase coolant fluid and one or more overlying layers of single-phase coolant fluids. The dual-phase and single-phase coolant fluids are immiscible, with the dual-phase coolant fluid having a lower boiling point and higher density than the single-phase coolant fluid. A substrate of an electronic system is submerged in the tank such that one or more high heat-generating components mounted on the substrate are immersed at least in the layer of the dual-phase coolant fluid. Heat from the components is dissipated to the dual-phase coolant fluid to generate vapor bubbles of the dual-phase coolant fluid. The vapor bubbles rise to a layer of a single-phase coolant fluid that is above the layer of the dual-phase coolant fluid. In the layer of the single-phase coolant fluid, the vapor bubbles condense to droplets of the dual-phase coolant fluid. The droplets fall down into the layer of the dual-phase coolant fluid.

(5) These and other features of the present invention will be readily apparent to persons of ordinary

skill in the art upon reading the entirety of this disclosure, which includes the accompanying drawings and claims.

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## Description

### DESCRIPTION OF THE DRAWINGS

- (1) FIG. 1 shows a schematic diagram of a fluid immersion cooling system in accordance with an embodiment of the present invention.
- (2) FIG. 2 shows a flow diagram of an operation of the fluid immersion cooling system of FIG. 1 in accordance with an embodiment of the present invention.
- (3) FIG. 3 shows a schematic diagram of the fluid immersion cooling system of FIG. 1 in accordance with an embodiment of the present invention.
- (4) FIG. 4 shows a schematic diagram of a fluid tank containing multiple layers of coolant fluids in accordance with an embodiment of the present invention.
- (5) FIG. 5 shows a flow diagram of a method of cooling an electronic system in accordance with an embodiment of the present invention.
- (6) The use of the same reference label in different drawings indicates the same or like components. The drawings are not to scale.

### DETAILED DESCRIPTION

- (7) In the present disclosure, numerous specific details are provided, such as examples of apparatus, components, and methods, to provide a thorough understanding of embodiments of the invention. Persons of ordinary skill in the art will recognize, however, that the invention can be practiced without one or more of the specific details. In other instances, well-known details are not shown or described to avoid obscuring aspects of the invention.
- (8) FIG. 1 shows a schematic diagram of a fluid immersion cooling system **100** in accordance with an embodiment of the present invention. The fluid immersion cooling system **100** includes a fluid tank **140** that contains a layer of a dual-phase coolant fluid **110** and a layer of a single-phase coolant fluid **120**. Both of the coolant fluids **110** and **120** are electrically non-conductive. The coolant fluids **110** and **120** are immiscible, with the liquid density of the coolant fluid **110** being higher than that of the coolant fluid **120**. The coolant fluids **110** and **120** thus exist as separate fluid layers in the tank **140**. The layer of the coolant fluid **110** is at the bottom of the tank **140** and the layer of the coolant fluid **120** is above the layer of the coolant fluid **110**.
- (9) The coolant fluid **110** is a “dual-phase” fluid in that it has a relatively low boiling point, which may be in the range of 40° C. to 80° C. The coolant fluid **110** may have an operating environment temperature that is equal to or near its boiling point. The coolant fluid **110** has a lower boiling point but a higher density than the coolant fluid **120**. Preferably, the coolant fluid **110** has as low viscosity as possible and a dielectric constant that is as close to 1 (vacuum value) as possible. The coolant fluid **110** may be a fluorochemical fluid. For example, the coolant fluid **110** may be the 3M™ Fluorinert™ Electronic Liquid, such as the product FC-3284, which is commercially available from the 3M Company. Other suitable dual-phase coolant fluids may also be employed.
- (10) The coolant fluid **120** is a “single-phase” fluid in that it has a relatively high boiling point, which may be higher than 80° C. The coolant fluid **120** has a higher boiling point but a lower density than the coolant fluid **110**. The coolant fluid **120** has an operating environment temperature that is lower than the boiling point of the coolant fluid **110**. Preferably, the coolant fluid **120** has as high viscosity as possible and a dielectric constant that is as close to 1 (vacuum value) as possible. A relatively high viscosity advantageously allows for better containment of vapor bubbles that rise from the coolant fluid **110**. The coolant fluid **120** may comprise a dielectric oil. For example, the coolant fluid **120** may be the ElectroCool™ coolant, which is commercially available from Engineered Fluids, LLC. Other suitable single-phase coolant fluids may also be employed.

(11) As shown in FIG. 1, a plurality of substrates **101** containing electronic devices **102** are placed in the tank **140**. The substrates **101** may comprise printed circuit boards or other substrates of an electronic system, such as an Information Technology (IT) equipment. The electronic devices **102** are examples of heat spots, which are regions or components that generate a lot of heat. An electronic device **102** may be a Central Processing Unit (CPU), Graphics Processing Unit (GPU), power transistor, Field Programmable Gate Array (FPGA), etc. In one embodiment, the heat spots are completely immersed at least in the coolant fluid **110**, whereas the rest of the substrates **101** are immersed in the coolant fluid **120**. In the example of FIG. 1, in the tank **140**, the coolant fluid **110** has a depth D1 and the coolant fluid **120** has a depth D2. The depth D1 may be much shallower than the depth D2 to conserve the relatively expensive coolant fluid **110** and to better prevent vapors of the coolant fluid **110** from escaping through the coolant fluid **120**. A dash line represents a boundary **105** between the coolant fluids **110** and **120**.

(12) The substrates **101**, being part of an electronic system, may be electrically interconnected by a motherboard, cables, etc. These interconnection components are not shown for clarity of illustration. During operation of the electronic system, the electronic devices **102** are powered ON and generate heat. Heat from the electronic devices **102** and other regions of the substrates **101** that are immersed in the coolant fluid **110** vaporizes the coolant fluid **110**, thereby generating vapor bubbles **103** of the coolant fluid **110**. The vapor bubbles **103** (depicted as white circles) rise and cross the boundary **105** into the layer of the coolant fluid **120**. The coolant fluid **120** prevents the vapor bubbles **103** from leaking through. The higher the viscosity of the coolant fluid **120**, the better the containment of the vapor bubbles **103**. Besides preventing leakage, the coolant fluid **120** also conserves the relatively expensive coolant fluid **110**.

(13) In the layer of the coolant fluid **120**, the vapor bubbles **103** condense into droplets **104** of the coolant fluid **110**. The droplets **104** (depicted as small dark circles) eventually fall down and cross the boundary **105** back into the layer of the coolant fluid **110**, completing the cooling cycle.

(14) The tank **140** may be an open container and does not necessarily need to be sealed. The tank **140** may have provisions for accepting wiring and plumbing and for facilitating access to the substrates **101**. Optionally, the fluid immersion cooling system **100** may include a condenser unit **141** that is configured to collect vapor bubbles **104** that have escaped through the layer of the coolant fluid **120**. The condenser unit **141** may be positioned right above the coolant fluid **120** in the tank **140** to trap escaping vapor bubbles **104**.

(15) Optionally, as an additional cooling mechanism, the tank **140** may include an inlet **142** and an outlet **143**. A cooler unit (not shown) may supply cool coolant fluid **120** to the tank **140** through the inlet **142** (see arrow **106**). Hot coolant fluid **120** may flow out of the tank **140** through the outlet **143** (see arrow **107**) to be cooled by the cooler unit. The cooler unit is a piece of equipment that is configured to cool hot coolant fluid.

(16) FIG. 2 shows a flow diagram of an operation of the fluid immersion cooling system **100** in accordance with an embodiment of the present invention. In the example of FIG. 2, the boundary **105** separates operations occurring in the layer of the dual-phase coolant fluid **110** (below the boundary **105**) and operations occurring in the layer of the single-phase coolant fluid **120** (above the boundary **105**).

(17) In the example of FIG. 2, an electronic system is placed in the tank **140**, which contains the layer of the coolant fluid **110** and the layer of the coolant fluid **120** (see FIG. 1). Heat from the electronic system dissipates to (FIG. 2, **201**) and vaporizes (FIG. 2, **202**) the coolant fluid **110**, which as previously described is a dual-phase fluid. The vaporization results in formation of vapor bubbles of the coolant fluid **110** (FIG. 2, **203**). The vapor bubbles rise across the boundary **105** (FIG. 2, **204**) and into the layer of the coolant fluid **120** (FIG. 2, **205**), which as previously described is a single-phase fluid. In the layer of the coolant fluid **120**, the vapor bubbles condense into droplets of the coolant fluid **110** (FIG. 2, **206**). In the coolant fluid **120**, the droplets fall down toward the layer of the coolant fluid **110** (FIG. 2, **207**). The droplets fall across the boundary **105**

and into the layer of the coolant fluid **110** (FIG. 2, **208**).

(18) In an experiment, a graduated cylinder was filled with the 3M™ FC-3284 Fluorinert™ Electronic Liquid as a bottom layer of dual-phase coolant fluid and with a GRC dielectric oil as an upper layer of single-phase coolant fluid. The GRC dielectric oil is commercially-available from the Green Revolution Cooling company. The single-phase coolant fluid has a lower density and a higher viscosity than the dual-phase coolant fluid. The dual-phase coolant fluid has a boiling point of about 50° C. The single-phase coolant fluid has a relatively high boiling point, which was not reached during the experiment.

(19) In the experiment, the graduated cylinder simulates a fluid tank. To simulate a cooler unit, a metal can containing ice was placed on the top of the graduated cylinder in the layer of single-phase coolant fluid. The bottom of the graduated cylinder was heated to simulate a heat spot. During the experiment, it was observed that heating the bottom of the graduated cylinder resulted in vapor bubbles of the dual-phase coolant fluid, which rose up to the single-phase coolant fluid. The vapor bubbles condensed into droplets in the single-phase coolant fluid, and the droplets fell back into the dual-phase coolant fluid as described in the flow diagram of FIG. 2. No leakage was observed during the experiment. The vapor bubbles were easily contained in the layer of single-phase coolant fluid to condense without vapor escape.

(20) FIG. 3 shows a schematic diagram of the fluid immersion cooling system **100** in accordance with an embodiment of the present invention. In the example of FIG. 3, the fluid immersion cooling system **100** includes a cooler unit comprising a manifold **153**, one or more pumps **151**, and a heat exchanger **152** (e.g., plate heat exchanger (PHE)) that is in-line with the pump **151**. The pump **151** may be disposed on the hot-side (as shown in FIG. 3), cold-side, or both sides (see FIG. 3, additional pump **151** represented by dashed lines) of the plumbing between the tank **140** and the heat exchanger **152**. In operation, the pump **151** circulates the coolant fluid **120** (i.e., single-phase coolant fluid) through the tank **140**. Cold coolant fluid **120** enters the tank **140** through the inlet **142** (see also FIG. 1, **142**) and hot coolant fluid **120** exits the tank **140** through the outlet **143**. The manifold **153** facilitates cooling of the coolant fluid **120**. The heat exchanger **152** further cools the coolant fluid **120** using cold water provided by an external cold water supply (not shown).

(21) As can be appreciated, two or more layers of coolant fluids may be used to cool an electronic system in accordance with the teachings of the present disclosure. The layers of coolant fluids may comprise a bottom dual-phase coolant fluid layer and a plurality of single-phase coolant fluid layers on top of the bottom dual-phase coolant fluid layer. For example, as illustrated in FIG. 4, the tank **140** may be filled with a bottom dual-phase coolant fluid layer **161** and upper single-phase coolant fluid layers **162** (i.e., **162-1**, **162-2**, **162-3**, . . . , **162-n**). The single-phase coolant fluid layers **162** are “upper” layers relative to the dual-phase coolant fluid layer **161**.

(22) The properties of the dual-phase and single-phase coolant fluids may be as described above with reference to the coolant fluids **110** and **120**. More particularly, the dual-phase coolant fluid layer **161** and single-phase coolant fluid layers **162** are immiscible, with the dual-phase coolant fluid layer **161** having higher density, lower viscosity, and much lower boiling than any of the single-phase coolant fluid layers **162**. The single-phase coolant fluid layers **162** have different densities and are immiscible to allow for different levels of layering over the dual-phase coolant fluid layer **161** and may have different viscosities to facilitate condensation of vapor bubbles of the dual-phase coolant fluid layer **161**.

(23) FIG. 5 shows a flow diagram of a method of cooling an electronic system in accordance with an embodiment of the present invention. In the example of FIG. 5, an electronic system is placed in a fluid tank containing a bottom layer of dual-phase coolant fluid and one or more upper layers of single-phase coolant fluids. High heat generating components of the electronic system are submerged at least in the bottom layer of dual-phase coolant fluid (FIG. 5, **301**). Heat from the components of the electronic system dissipates to the dual-phase coolant fluid to generate vapor bubbles of the dual-phase coolant fluid (FIG. 5, **302**). The vapor bubbles rise to at least one of the

upper layers of single-phase coolant fluids (FIG. 5, 303). In a layer of single-phase coolant fluid, the vapor bubbles condense to droplets of the dual-phase coolant fluid (FIG. 5, 304). The droplets fall down toward the layer of dual-phase coolant fluid (FIG. 5, 305).

(24) A fluid immersion cooling system for cooling electronic systems have been disclosed. While specific embodiments of the present invention have been provided, it is to be understood that these embodiments are for illustration purposes and not limiting. Many additional embodiments will be apparent to persons of ordinary skill in the art reading this disclosure.

## Claims

1. A fluid immersion cooling system comprising: a fluid tank containing a component of an electronic system; a layer of a dual-phase coolant fluid in the fluid tank, the layer of the dual-phase coolant fluid is in liquid state, the component of the electronic system is immersed at least in the layer of the dual-phase coolant fluid; and a layer of a single-phase coolant fluid that is over the layer of the dual-phase coolant fluid in the fluid tank, the layer of the single-phase coolant fluid is in liquid state, the layer of the single-phase coolant fluid and the layer of the dual-phase coolant fluid are immiscible, a liquid density of the layer of the dual-phase coolant fluid is higher than a liquid density of the layer of the single-phase coolant fluid, and a boiling point of the layer of the dual-phase coolant fluid is lower than a boiling point of the layer of the single-phase coolant fluid.
2. The fluid immersion cooling system of claim 1, wherein the layer of the single-phase coolant fluid comprises a dielectric oil.
3. The fluid immersion cooling system of claim 1, wherein the layer of the dual-phase coolant fluid comprises a fluorochemical.
4. The fluid immersion cooling system of claim 1, further comprising: a cooler unit that is coupled to an outlet and an inlet of the fluid tank.
5. The fluid immersion cooling system of claim 4, wherein the cooler unit comprises: a pump; and a heat exchanger.
6. The fluid immersion cooling system of claim 1, further comprising: a condenser that is disposed above the layer of the single-phase coolant fluid.
7. The fluid immersion cooling system of claim 1, wherein the component of the electronic system is a central processing unit (CPU).
8. The fluid immersion cooling system of claim 1, wherein the tank is an open container.
9. A method of cooling an electronic system, the method comprising: submerging a component of an electronic system in a layer of a dual-phase coolant fluid that is in liquid state in a fluid tank; dissipating heat from the component of the electronic system to the layer of the dual-phase coolant fluid to generate vapor bubbles of the layer of the dual-phase coolant fluid; and condensing the vapor bubbles of the layer of the dual-phase coolant fluid in a layer of a single-phase coolant fluid in the fluid tank, the layer of the single-phase coolant fluid is over the layer of the dual-phase coolant fluid in the fluid tank, the layer of the single-phase coolant fluid is in liquid state, wherein the layer of the dual-phase coolant fluid and the layer of the single-phase coolant fluid are immiscible, a liquid density of the layer of the dual-phase coolant fluid is higher than a liquid density of the layer of the single-phase coolant fluid, and a boiling point of the layer of the dual-phase coolant fluid is lower than a boiling point of the layer of the single-phase coolant fluid.
10. The method of claim 9, further comprising: collecting and condensing, in a condenser unit, vapor bubbles of the dual-phase coolant fluid that have not been contained in the layer of the single-phase coolant fluid, the condenser unit is disposed above the layer of the single-phase coolant fluid.
11. The method of claim 9, wherein the layer of the dual-phase coolant fluid comprises a fluorochemical.

12. The method of claim 9, wherein the layer of the single-phase coolant fluid comprises a dielectric oil.

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